



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Gu-Sung KIM

Art Unit: 2814

Serial No. 10/073,173

Examiner: Long Pham

Filed: February 13, 2002

Confirmation No. 4677

For: WAFER LEVEL PACKAGE WITH AIR PADS AND  
MANUFACTURING METHOD THEREOF

**INFORMATION DISCLOSURE STATEMENT**  
**UNDER 37 C.F.R. §1.56**

Commissioner for Patents  
Alexandria, VA 22313-1450

Sir:

Submitted herewith on Form PTO/SB/08 (or PTO-1449, *modified*) is a listing of a document(s) known to applicant in order to comply with applicant's duty of disclosure pursuant to 37 C.F.R. §1.56.

☒ A copy of each listed document is being submitted to comply with the provisions of 37 C.F.R. §§1.97 & 1.98. [Box checked if applicable.]

☒ A copy of each listed non-U.S. patent and/or patent publication and cited literature is being submitted to comply with the provisions of 37 C.F.R. §§1.97 & 1.98. Cited U.S. patents and patent publications are *not* attached in accordance with the waiver set forth in the Notice by the Deputy Commissioner for Patent Examination Policy dated July 11, 2003, applicable to applications having a U.S. filing date *after* June 30, 2003. [Box checked if applicable.]

\* \* \*

The submission of any document herewith, which is not a statutory bar, is not intended as an admission that such document constitutes prior art against the claims of the present application. Applicant does not waive any rights to take any action that would be appropriate to

antedate or otherwise remove as a competent reference any document which is determined to be a *prima facie* prior art reference against the claims of the present application.

☒ The listed document(s) is/are being submitted in compliance with 37 C.F.R. 1.97(b)(3): submission before the mailing date of the first action on the merits. [Box checked if applicable.]

☐ The foregoing document came to applicant's attention during the prosecution of their corresponding \_\_\_\_\_ application. ☐ A copy of the \_\_\_\_\_ Search Report is also attached. [Box(es) checked if applicable.]

#### CERTIFICATION

☐ The undersigned hereby certifies in accordance with 37 CFR §1.97(e)(1) that each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three (3) months prior to the filing of this Statement. [Box checked if applicable.]

\* \* \*

Applicant respectfully requests that the listed document(s) be considered by the Examiner and be made of record in the present application and that an initialed copy of Form PTO/SB/08 be returned in accordance with MPEP §609.


\* \* \*

#### FFF PAYMENT

- ☐ The fee mandated by 37 C.F.R. §1.17(p) is believed applicable. [Box checked if applicable.]
- ☐ Attached is a check in payment of this fee (\$180.00). [Box checked if applicable.]
- ☐ This fee may be charged to Deposit Account No. 50-1645. (A duplicate copy of this paper is enclosed.) [Box checked if applicable.]

Respectfully submitted,

September 2, 2003  
Date

  
\_\_\_\_\_  
Eugene M. Lee  
Registration No. 32,039  
Richard A. Sterba  
Registration NO. 43,162

LEE & STERBA, P.C.  
1101 WILSON BOULEVARD, SUITE 2000  
ARLINGTON, VA 22209  
703.525.0978 TEL  
703.525.4265 FAX

**DEPOSIT ACCOUNT CHARGE AUTHORIZATION**

If fee payment is enclosed, this amount is believed to be correct. However, the Director is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-1645.

Any additional fee(s) necessary to effect the proper and timely filing of the above-paper may also be charged to Deposit Account No. 50-1645.

U.S. DEPARTMENT OF COMMERCE



ATTY DOCKET NO.  
259/014

SERIAL NO.  
10/073,173

APPLICANT  
Gu Sung KIM

FILING DATE  
February 13, 2002

GROUP  
2814

## U.S. PATENT DOCUMENTS

[illegible]

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO

OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)

			KOHL, Paul A.; MARTIN, Kevin, "Wafer-Level Packaging Addresses Chip-to-Module Interconnections"
			Semiconductor International, CAHNERS Business Information, Reed Elsevier, Inc. (April 2001)
			KOHL, Paul A., et al, "Air-Gaps for Electrical Interconnections": Electrochemical and Solid-State
			Letters, 1(1):49-51, The Electrochemical Society, Inc. (1998)

**EXAMINER**

DATE CONSIDERED

**\*EXAMINER:** Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.